

May 2000



# FQAF19N20L

## 200V LOGIC N-Channel MOSFET

## **General Description**

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supply, motor control.

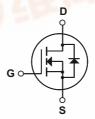
#### **Features**

- 16A, 200V,  $R_{DS(on)} = 0.14\Omega @V_{GS} = 10 \text{ V}$
- Low gate charge (typical 27 nC)
- Low Crss (typical 30 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability
- · Low level gate drive requirement allowing direct operation from logic drivers



GDS

TO-3PF **FQAF** Series



## Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

| Symbol                            | Parameter  |          | FQAF19N20L  | Units |  |
|-----------------------------------|--|----------|-------------|-------|--|
| V <sub>DSS</sub>                  | Drain-Source Voltage                               | 1900     | 200         | V     |  |
| I <sub>D</sub>                    | Drain Current - Continuous (T <sub>C</sub> = 25°C) | 0=1///   | 16          | А     |  |
|                                   | - Continuous (T <sub>C</sub> = 100°C)              |          | 10.1        | А     |  |
| I <sub>DM</sub>                   | Drain Current - Pulsed                             | (Note 1) | 64          | А     |  |
| V <sub>GSS</sub>                  | Gate-Source Voltage                                |          | ± 20        | V     |  |
| E <sub>AS</sub>                   | Single Pulsed Avalanche Energy                     | (Note 2) | 250         | mJ    |  |
| I <sub>AR</sub>                   | Avalanche Current                                  | (Note 1) | 16          | Α     |  |
| E <sub>AR</sub>                   | Repetitive Avalanche Energy                        | (Note 1) | 8.5         | mJ    |  |
| dv/dt                             | Peak Diode Recovery dv/dt (Note 3)                 |          | 5.5         | V/ns  |  |
| P <sub>D</sub>                    | Power Dissipation (T <sub>C</sub> = 25°C)          |          | 85          | W     |  |
|                                   | - Derate above 25°C                                |          | 0.68        | W/°C  |  |
| T <sub>J</sub> , T <sub>STG</sub> | Operating and Storage Temperature Range            |          | -55 to +150 | °C    |  |
| TL                                | Maximum lead temperature for soldering purposes,   |          | 300         | °C    |  |
| 'L                                | 1/8" from case for 5 seconds                       | 300      |             |       |  |

| Thermal Characteristics Thermal Characteristics |   |     |      |       |  |
|---|---|-----|------|-------|--|
| Symbol  | Parameter                               | Тур | Max  | Units |  |
| $R_{\theta JC}$                                 | Thermal Resistance, Junction-to-Case    |     | 1.47 | °C/W  |  |
| $R_{\theta JA}$                                 | Thermal Resistance, Junction-to-Ambient |     | 40   | °C/W  |  |

| Symbol                           | Parameter   | Test Conditions   |             | Min | Тур  | Max  | Units |
|----------------------------------|---|---|-------------|-----|------|------|-------|
| Off Cha                          | racteristics  |   |             |     |      |      |       |
| BV <sub>DSS</sub>                | Drain-Source Breakdown Voltage                        | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$                               |             | 200 |      |      | V     |
| $\Delta BV_{DSS}$ / $\Delta T_J$ | Breakdown Voltage Temperature<br>Coefficient          | I <sub>D</sub> = 250 μA, Referenced t                                       | to 25°C     |     | 0.16 |      | V/°C  |
| I <sub>DSS</sub>                 | Zero Gate Voltage Drain Current                       | V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V                              |             | -   |      | 1    | μΑ    |
|                                  |   | V <sub>DS</sub> = 160 V, T <sub>C</sub> = 125°C                             |             | -   |      | 10   | μΑ    |
| I <sub>GSSF</sub>                | Gate-Body Leakage Current, Forward                    | V <sub>GS</sub> = 20 V, V <sub>DS</sub> = 0 V                               |             | -   | -    | 100  | nA    |
| I <sub>GSSR</sub>                | Gate-Body Leakage Current, Reverse                    | V <sub>GS</sub> = -20 V, V <sub>DS</sub> = 0 V                              |             |     |      | -100 | nA    |
| On Cha                           | racteristics  |   |             |     |      |      |       |
| V <sub>GS(th)</sub>              | Gate Threshold Voltage                                | $V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$                                  |             | 1.0 |      | 2.0  | V     |
| R <sub>DS(on)</sub>              | Static Drain-Source                                   | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 8.0 A                              |             |     | 0.11 | 0.14 |       |
| DO(OII)                          | On-Resistance   | $V_{GS} = 5 \text{ V}, I_D = 8.0 \text{ A}$                                 | (Note 4)    |     | 0.12 | 0.15 | Ω     |
| 9 <sub>FS</sub>                  | Forward Transconductance                              | V <sub>DS</sub> = 30 V, I <sub>D</sub> = 8.0 A                              |             |     | 16   |      | S     |
| <b>Dynam</b>                     | ic Characteristics Input Capacitance                  | V - 25 V V - 0 V  |             |     | 1700 | 2200 | pF    |
| C <sub>oss</sub>                 | Output Capacitance                                    | $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$<br>f = 1.0 MHz               |             |     | 220  | 290  | pF    |
| C <sub>rss</sub>                 | Reverse Transfer Capacitance                          | 1 - 1.0 WH 12   |             | -   | 30   | 40   | pF    |
| Switchi                          | ng Characteristics                                    |   |             |     |      |      |       |
| t <sub>d(on)</sub>               | Turn-On Delay Time                                    | V <sub>DD</sub> = 100 V, I <sub>D</sub> = 21 A,                             |             |     | 35   | 80   | ns    |
| t <sub>r</sub>                   | Turn-On Rise Time                                     | $R_G = 25 \Omega$ (Note 4, 5)   |             |     | 300  | 610  | ns    |
| $t_{d(off)}$                     | Turn-Off Delay Time                                   |   |             |     | 130  | 270  | ns    |
| t <sub>f</sub>                   | Turn-Off Fall Time                                    |   |             |     | 180  | 370  | ns    |
| $Q_g$                            | Total Gate Charge                                     | $V_{DS} = 160 \text{ V}, I_D = 21 \text{ A}, V_{GS} = 5 \text{ V}$ (Note 4, |             |     | 27   | 35   | nC    |
| $Q_{gs}$                         | Gate-Source Charge                                    |   | (Note 4, 5) | -   | 5.8  |      | nC    |
| Q <sub>gd</sub>                  | Gate-Drain Charge                                     |   |             |     | 11.2 |      | nC    |
| Drain-S                          | Source Diode Characteristics a                        | nd Maximum Ratings  | ;           |     |      |      |       |
| I <sub>S</sub>                   | Maximum Continuous Drain-Source Diode Forward Current |   |             | -   | -    | 16   | Α     |
| I <sub>SM</sub>                  | Maximum Pulsed Drain-Source Diode F                   | kimum Pulsed Drain-Source Diode Forward Current                             |             |     |      | 64   | Α     |
| $V_{SD}$                         | Drain-Source Diode Forward Voltage                    | V <sub>GS</sub> = 0 V, I <sub>S</sub> = 16 A                                |             | I   | -    | 1.5  | ٧     |
| t <sub>rr</sub>                  | Reverse Recovery Time                                 | V <sub>GS</sub> = 0 V, I <sub>S</sub> = 21 A,                               | (Note 4)    | I   | 140  |      | ns    |
| Q <sub>rr</sub>                  | Reverse Recovery Charge                               | dl <sub>E</sub> / dt = 100 A/μs   |             | -   | 0.66 |      | μС    |

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 1.46mH, I<sub>AS</sub> = 16A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25 Ω, Starting T<sub>J</sub> = 25°C 3. I<sub>SD</sub>  $\leq$  21A, di/dt  $\leq$  300A/μs, V<sub>DD</sub>  $\leq$  BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C 4. Pulse Test : Pulse width  $\leq$  300μs, Duty cycle  $\leq$  2% 5. Essentially independent of operating temperature

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# **Typical Characteristics**

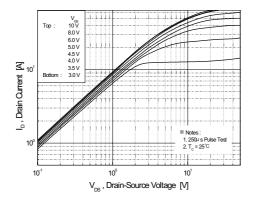


Figure 1. On-Region Characteristics

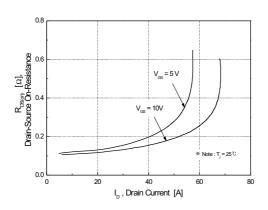


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

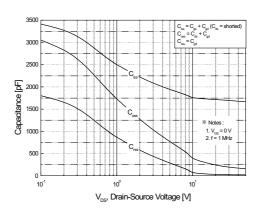


Figure 5. Capacitance Characteristics

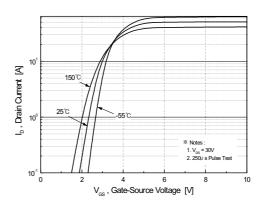


Figure 2. Transfer Characteristics

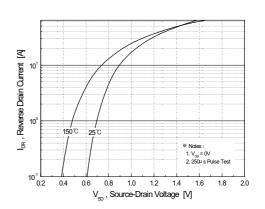


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

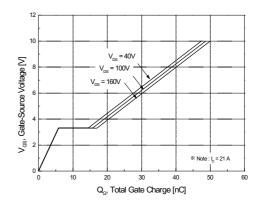


Figure 6. Gate Charge Characteristics

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# Typical Characteristics (Continued)

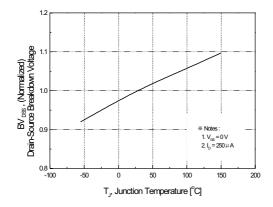
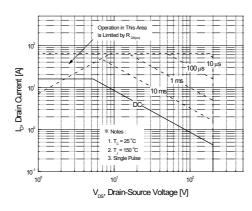


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



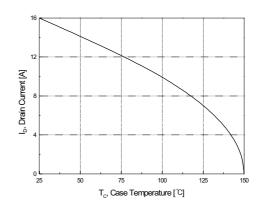


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

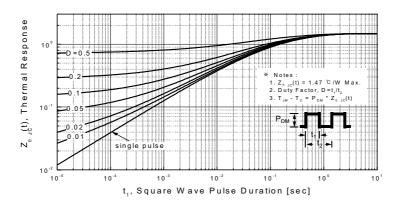
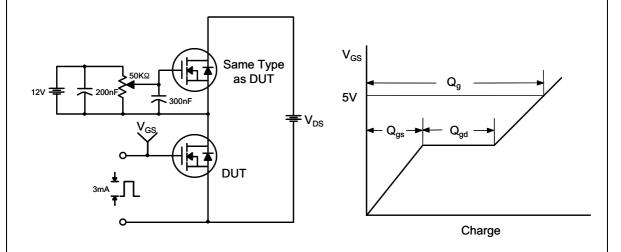


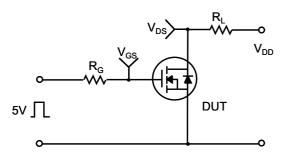
Figure 11. Transient Thermal Response Curve

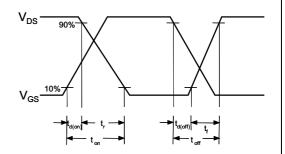
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## **Gate Charge Test Circuit & Waveform**

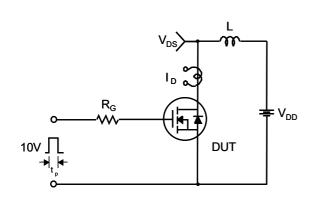


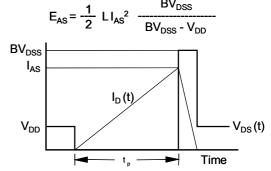
## **Resistive Switching Test Circuit & Waveforms**



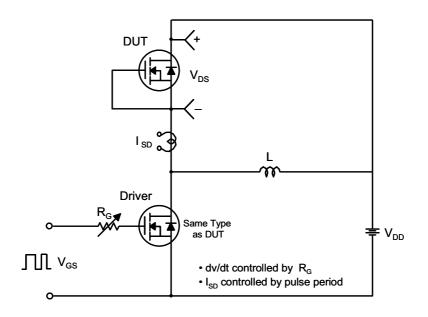


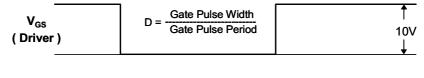
## **Unclamped Inductive Switching Test Circuit & Waveforms**

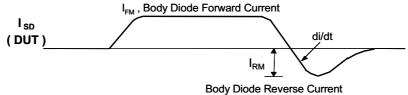


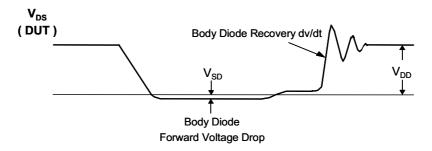


## Peak Diode Recovery dv/dt Test Circuit & Waveforms

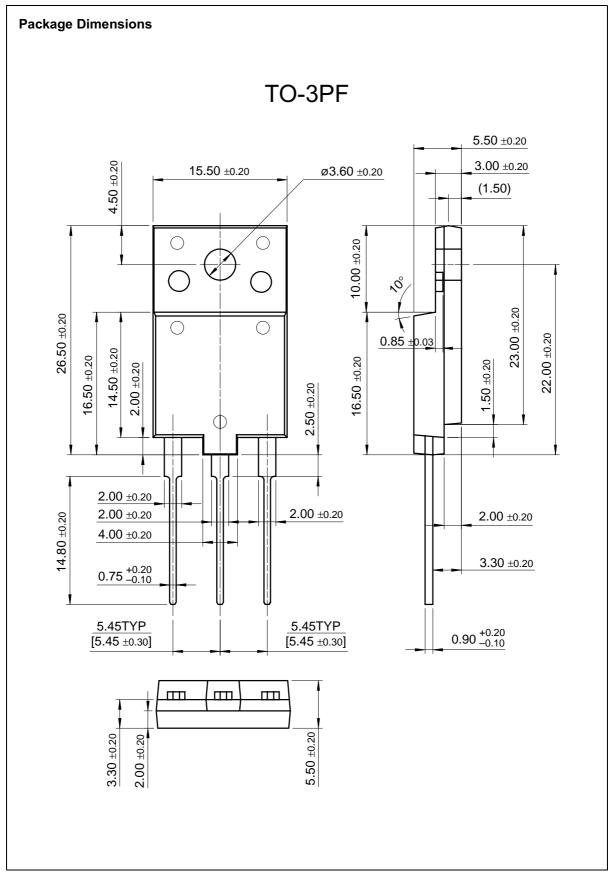








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